Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment

ATS PART # ATS-51310R-C2-R0

Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- Comes preassembled with high performance, phase changing, thermal interface material
- Designed for low profile components from 1.5 to 2.99mm

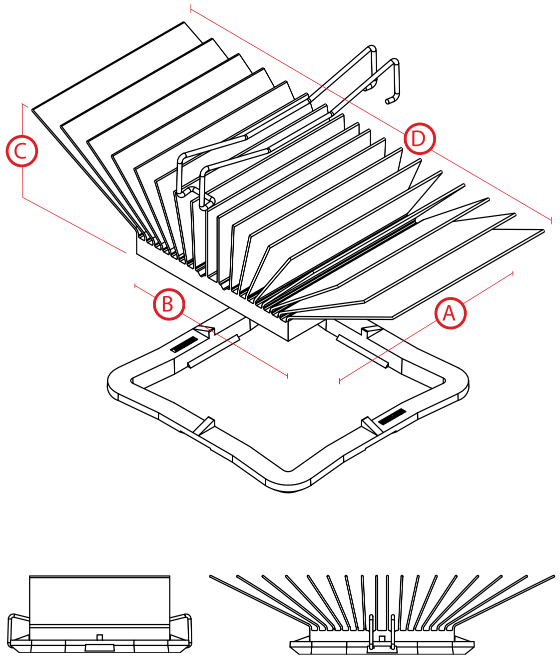

*Image above is for illustration purposes only.

Thermal Performance

AIR VELOCITY		THERMAL RESISTANCE	
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)
200	1.0	3.2	2.6
300	1.5	2.6	
400	2.0	2.3	
500	2.5	2.1	
600	3.0	1.9	
700	3.5	1.8	
800	4.0	1.7	

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
31 mm	31 mm	19.5 mm	54.9 mm	SAINT-GOBAIN C1100F	BLACK- ANODIZED

NOTES:

1) Dimension C = heat sink height from bottom of the base to the top of the fin field.
2) ATS-51310R-C1-R0 is a subsitute item available utilizing an equivalent phase change material (Chomerics T766).
3) Thermal performance data are provided for reference only. Actual performance may vary by application.
4) ATS reserves the right to update or change its products without notice to improve the design or performance.
5) Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT310
6) Contact ATS to learn about custom options available.

ATS ADVANCED THERMAL SOLUTIONS, INC.
Innovations in Thermal Management®

For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).

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